

Description

The SX3407MI uses advanced Trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = -30V$ $I_D = -4.8A$

$R_{DS(ON)} < 55m\Omega$ @ $V_{GS}=10V$

Application

Battery protection

Load switch

Uninterruptible power supply

**Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)**

Symbol	Parameter	Max.	Units
VDSS	Drain-Source Voltage	-30	V
VGSS	Gate-Source Voltage	± 20	V
$I_D @ T_c=25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-4.8	A
$I_D @ T_c=100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-3.3	A
IDM	Pulsed Drain Current ^{note1}	-20.4	A
P_D	Power Dissipation $T_A = 25^\circ C$	2.15	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	104	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance from Junction to Ambient ²	125	$^\circ C/W$
TJ, TSTG	Operating and Storage Temperature Range	-55 to +150	$^\circ C$

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=-250\mu\text{A}$	-30	-	-	V
IDSS	Zero Gate Voltage Drain Current	$V_{DS}=-30\text{V}, V_{GS}=0\text{V}$	-	-	-1	μA
IGSS	Gate-Source Leakage	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$	-	-	± 100	nA
VGS(th)	Gate-Source Threshold voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1	-1.5	-2.5	V
RDS(on)	Drain-Source on-State Resistance ³	$V_{GS}=-10\text{V}, I_D=-4.1\text{A}$	-	40	55	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}, I_D=-3\text{A}$	-	54	65	
Ciss	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=-15\text{V}, f=1.0\text{MHz}$	-	530	-	pF
Coss	Output Capacitance		-	70	-	
Crss	Reverse Transfer Capacitance		-	56	-	
Qg	Total Gate Charge	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, I_D=-4.1\text{A}$	-	6.8	-	nC
Qgs	Gate-Source Charge		-	1.0	-	
Qgd	Gate-Drain Charge		-	1.4	-	
td(on)	Turn-on Delay Time	$V_{GS}=-10\text{V}, V_{DS}=-15\text{V}, R_L=15\Omega, R_{GEN}=2.5\Omega$	-	14	-	ns
t _r	Rise Time		-	61	-	
td(off)	Turn-off Delay time		-	19	-	
t _f	Fall Time		-	10	-	
VSD	Diode Forward Voltage ³	$I_S=-4.1\text{A}, V_{GS}=0\text{V}$	-	-	-1.2	V
IS	Continuous Source Current		-	-	-4.1	A

Note :

- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3、The power dissipation is limited by 150°C junction temperature
- 4、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Typical Characteristics

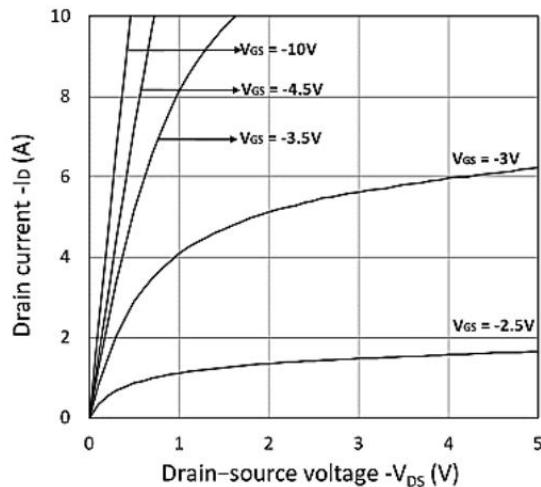


Figure 1. Output Characteristics

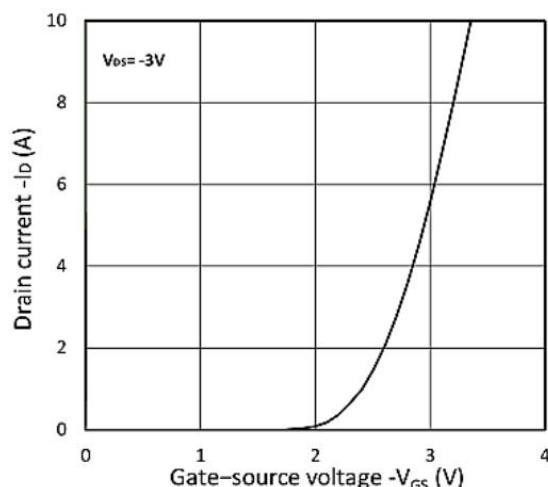


Figure 2. Transfer Characteristics

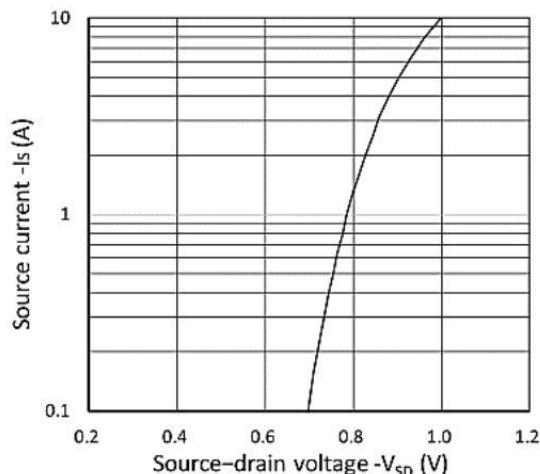


Figure 3. Forward Characteristics of Reverse

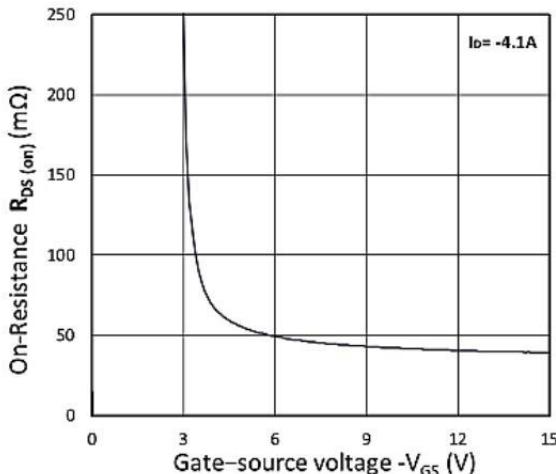


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

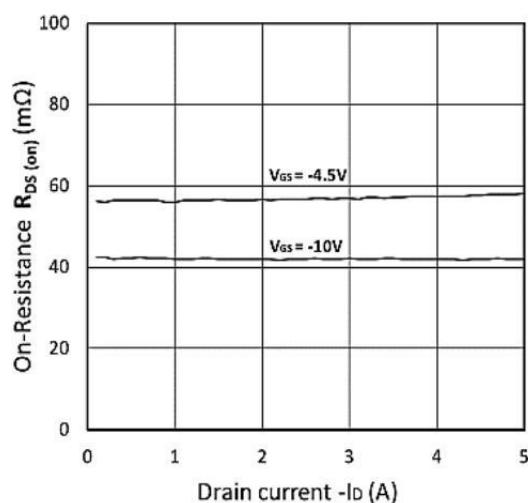


Figure 5. $R_{DS(ON)}$ vs. I_D

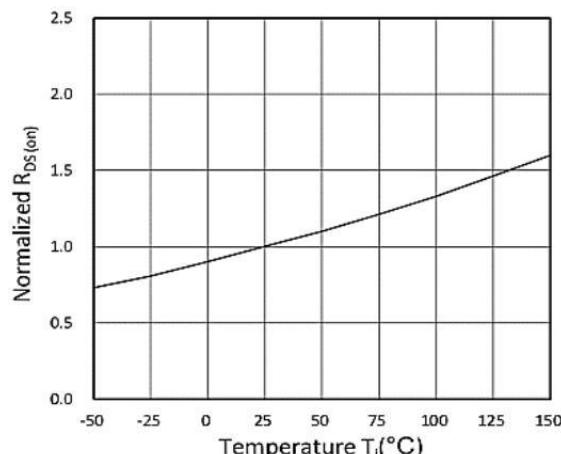


Figure 6. Normalized $R_{DS(ON)}$ vs. Temperature

Typical Characteristics

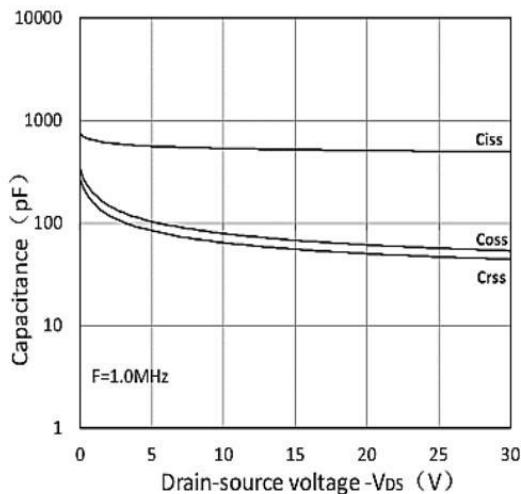


Figure 7. Capacitance Characteristics

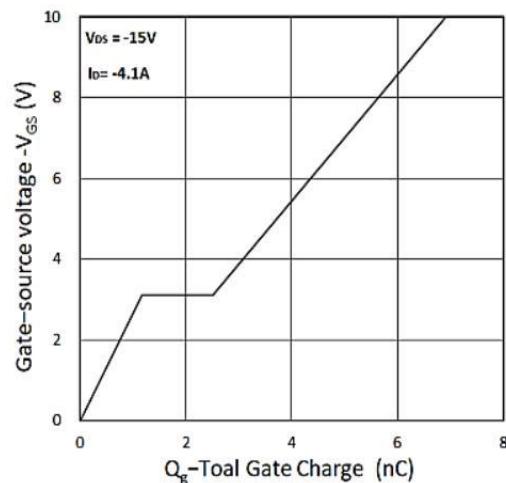


Figure 8. Gate Charge Characteristics

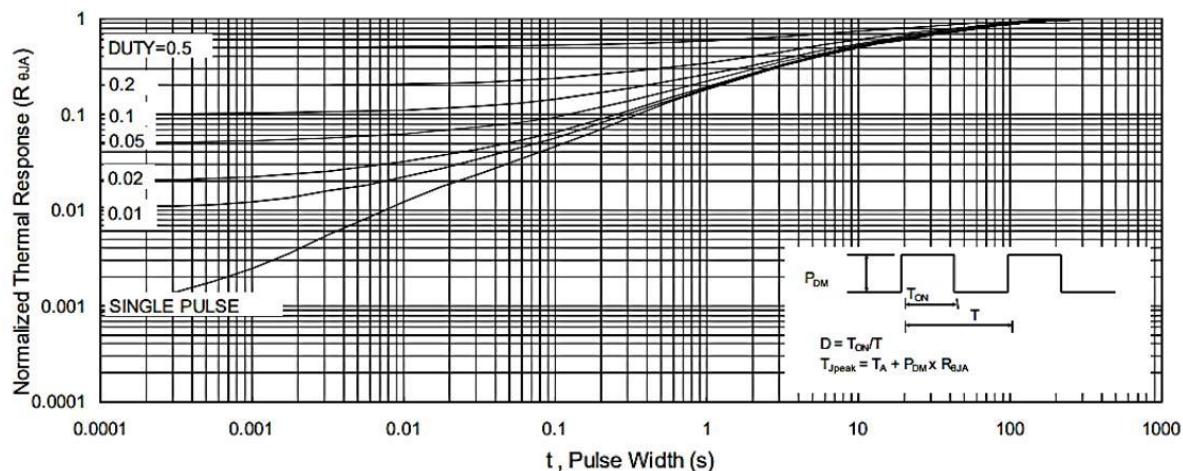


Figure 9 Normalized Maximum Transient Thermal Impedance

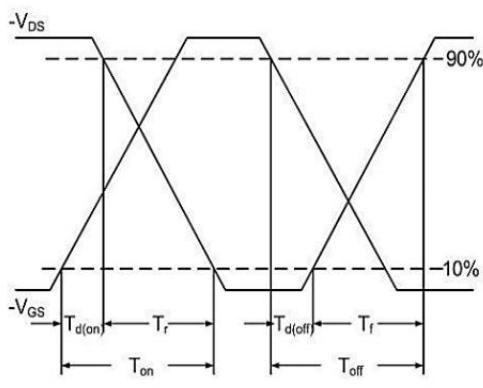


Figure.10 Switching Time Waveform

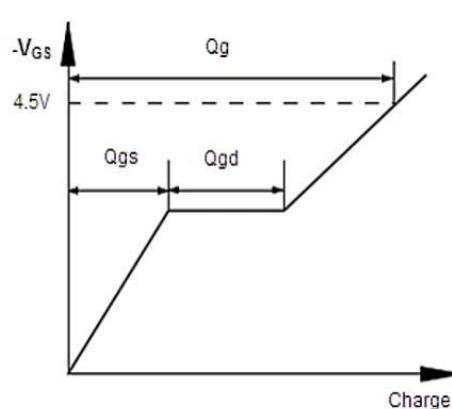
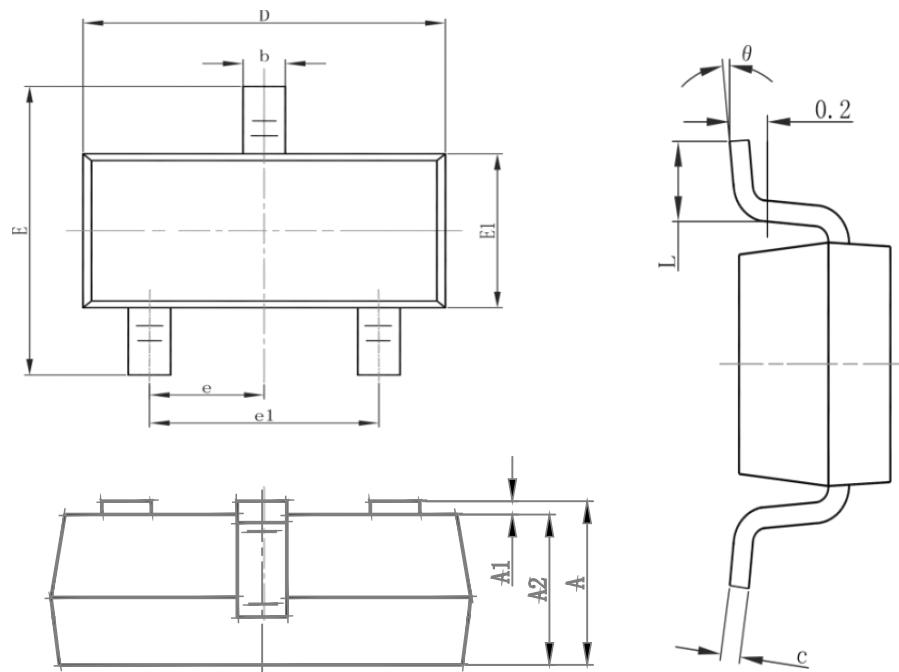


Figure.11 Gate Charge Waveform

Package Mechanical Data-SOT23-3-SLS-Single



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	SOT23-3L		3000